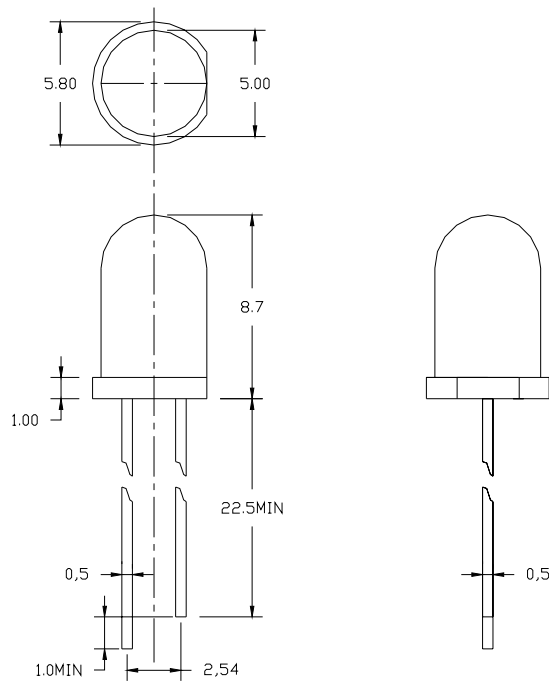


Features:

1. Low power consumption
2. High efficiency
3. Reliable and rugged
4. Chip Material: AlGaInP
5. Lens Color: Water Transparent
6. Source Color: RED

Outline Dimensions:



Note :

1. All dimensions are in millimeters (inches)
 2. Tolerance is $\pm 0.25\text{mm}$ (.010") unless otherwise noted
 3. Protruded resin under flange is 1.0mm (.04") max.
 4. Lead spacing is measured where the leads emerge from the package.
 5. Specifications are subject to change without notices.
-

Absolute Maximum Ratings at Ta=25 :

Parameter	Maximum	Unit
Power Dissipation	85	mW
Peak Forward Current (1/10 Duty Cycle,0.1ms Pulse Width)	100	mA
Continuous Forward Current	30	mA
Derating Linear From 50	0.5	mA/
Reverse Voltage	5	V
Operating Temperature Range	-20 to + 80	
Storage Temperature Range	-30 to + 100	
Lead Soldering Temperature [1.6mm(0.63") from body]	260 for 3 Seconds	

Electrical/Optical Characteristics at Ta=25

		Test Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	I_v	$I_F=20\text{mA}$	3000		5000	mcd
Dominant Wavelength	λ_d	$I_F=20\text{mA}$	620		630	nm
Viewing Angle	2 1/2	$I_F=20\text{mA}$	40		50	deg
Forward Voltage	V_F	$I_F=20\text{mA}$	1.9	2.0	2.5	V
Reverse Current	I_R	$V_R=5\text{V}$			100	uA

- **Typical Electrical/Optical Characteristics Curve: (25°C Ambient Temperature Unless Otherwise Noted)**

Fig1. Relative Intensity vs. Wavelength

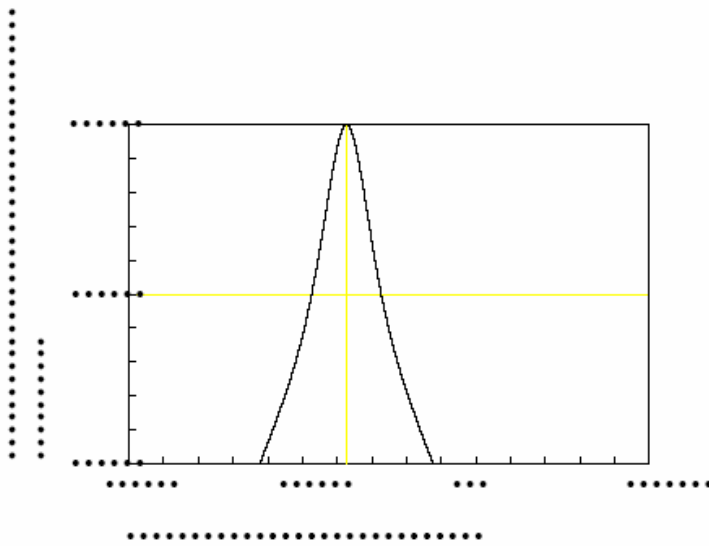


Fig2. Forward Current vs. Forward Voltage

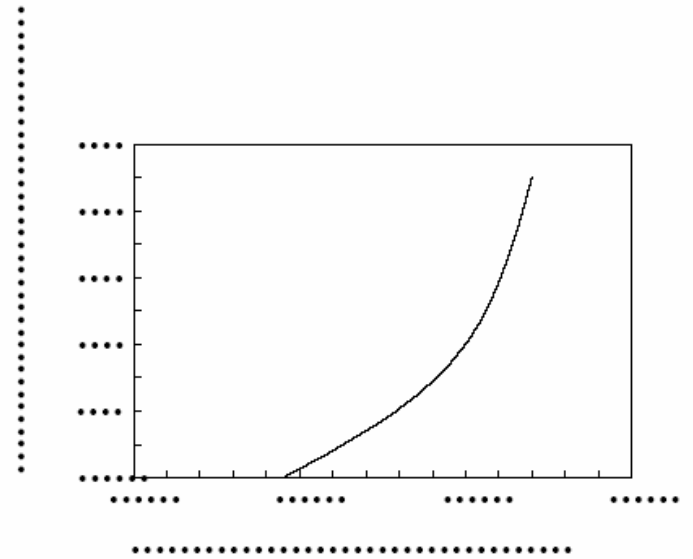


Fig3. Relative Intensity vs. Forward Current

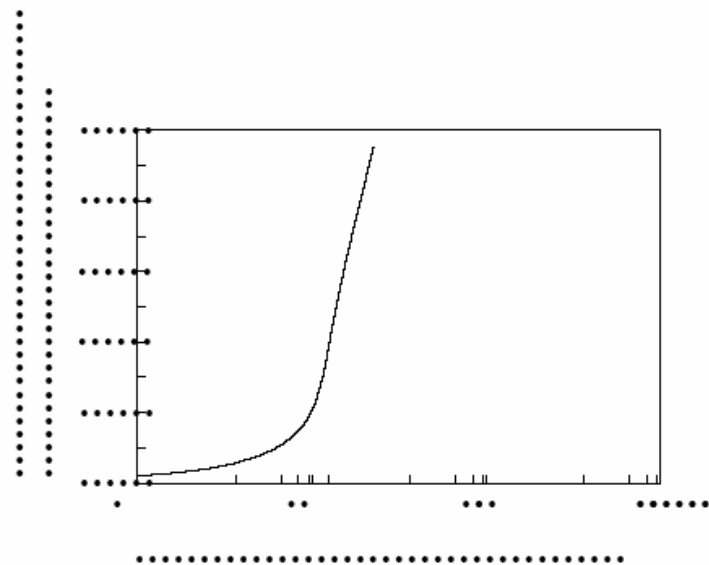


Fig4. Forward Voltage vs. Temperature

